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Application Number	10055560
Filing Date	2002-01-22
First Named Inventor	Mou-Shiung Lin
Art Unit	2813
Examiner Name	Mitchell, James M
Attorney Docket Number	MEGP0009USA

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1	JACOB MILLMAN, Digital and Analog Circuits and Systems, MICRO ELECTRONIC, March 1979, p.115 & p.167, Sec 4-11 & Sec 6-1, McGraw-Hill College.	<input type="checkbox"/>
2	Rao R. Tummala, Eugene J. Rymaszewski & Alan G. Klopfenstein, MICROELECTRONICS PACKAGING HANDBOOK (Second Edition), Technology Drivers Part I, January 31, 1997, p.12~13, p.64~65, p.82~87, p.133, An overview & 8-2 chip-level interconnection evolution, Springer.	<input type="checkbox"/>
3	John H. Lau & S.W. Ricky Lee, Chip Scale Package, General Electric's Chip-On-Flex Chip Scale Package (COF-CSP) , February 28, 1999, P0156~161, Chapter ten, McGraw-Hill Professional.	<input type="checkbox"/>

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